

IN THE U.S. PATENT AND TRADEMARK OFFICE

In re application of

Koichi OHTO

Conf. 4540

Application No. 10/622,645

Group 2813

Filed July 21, 2003

Examiner E. Kielin

METHOD FOR FORMING A CAPPING LAYER ON A COPPER INTERCONNECT

AMENDMENT

Assistant Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

April 6, 2005

Sir:

In response to the Official Action mailed December 6, 2004, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 4 of this paper.